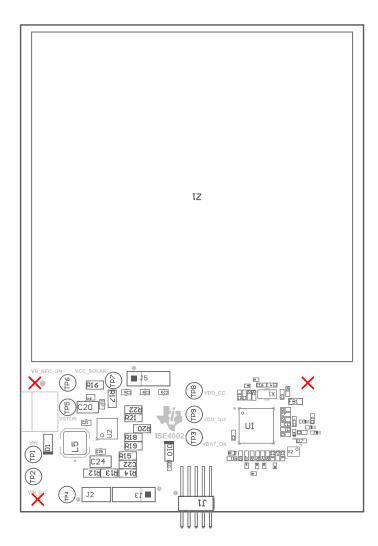
ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

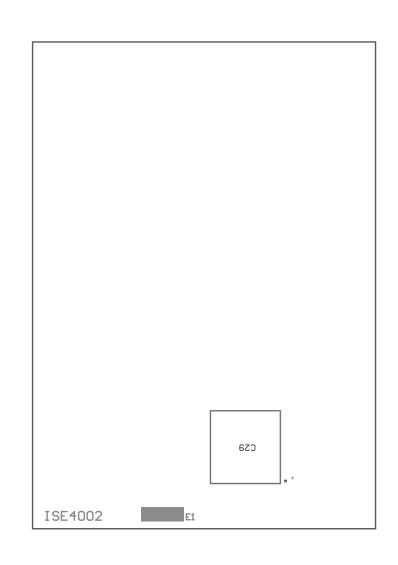
ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZI Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE		BOARD #: ISE4002	REV: E1	SUN REU	: Not In VersionControl
IGNORE ->	Top Overlay				
PLOT NAME =	Top Assembly Drawing	GENERATED : 3/12/2	2014 9: 58: 26	AM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: ISE4002	REV: E1	SUN REU	: Not In VersionControl	
	IGNORE -> ye		er lay	Bottom Overl	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/12/2	2014 9: 58: 26	AM	TEXAS INSTRUMENTS	

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